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Dimensions

Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	2.5mm +/-0.20mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	20

General Information

Series	SMD Indust COG HVHT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	320 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 30 - 70 micro inches.
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3600 pF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms